ON Semiconductor

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16927

Generic Copy

Issue Date: 08-Nov-2012

TITLE: Implementation of polyimide on WISB bare-die

PROPOSED FIRST SHIP DATE: 08-Feb-2013

AFFECTED CHANGE CATEGORY(S): Wafer Fab

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office, your Customer Quality interface: Jaromir Ftorek < Jaromir.Ftorek@onsemi.com >

SAMPLES: Contact your local ON Semiconductor Sales Office

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

Implementation of polyimide on WISB bare-die version in standard Onsemi polyimide process, as qualified by Onsemi (ref: Technology Early Production Qualification Report for I2T100 Polyimide Fab2 dd October 2006).

Implementation of polyimide is done in order to reduce mechanical damage to the die surface.

List of affected Customer Specific Parts:

0WISB-001-XSW
0WISB-002-XDW